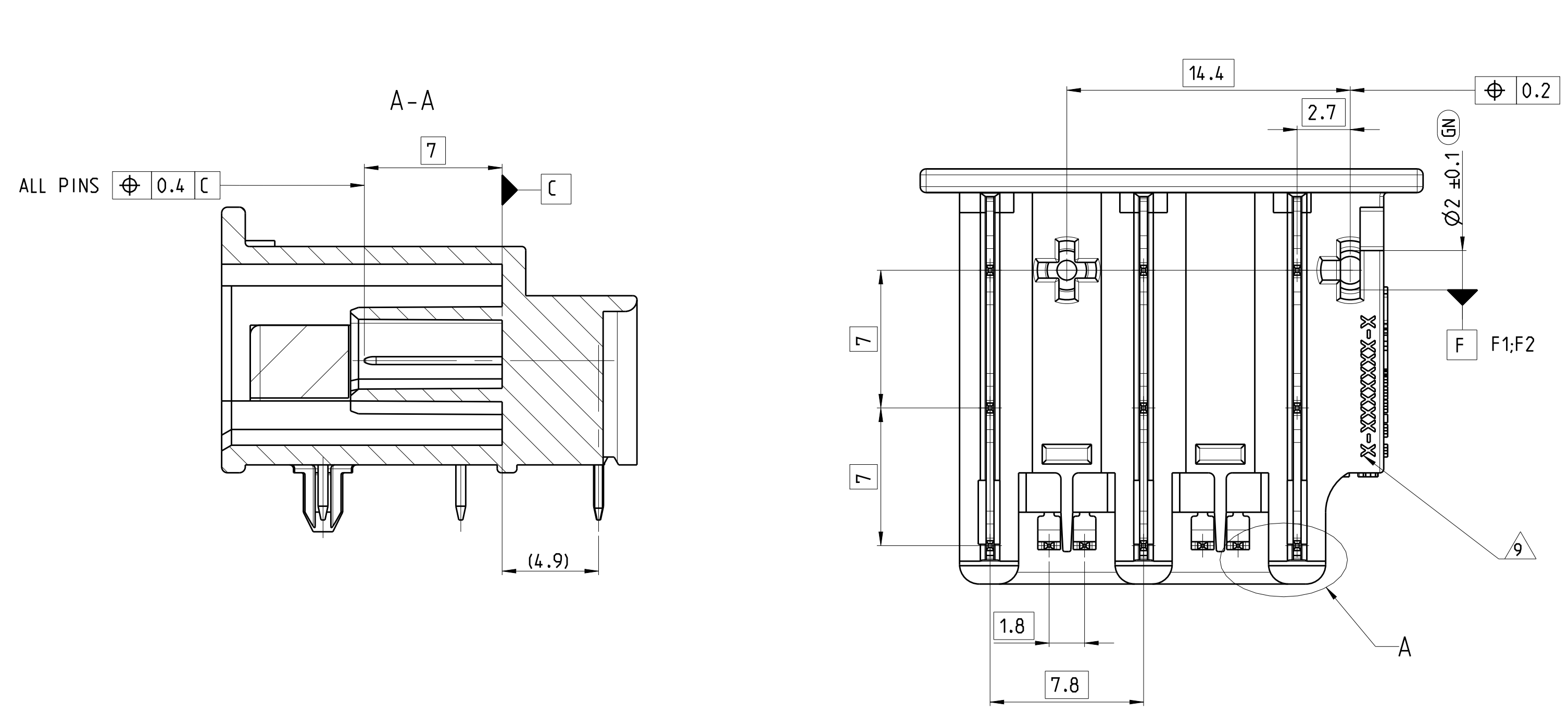
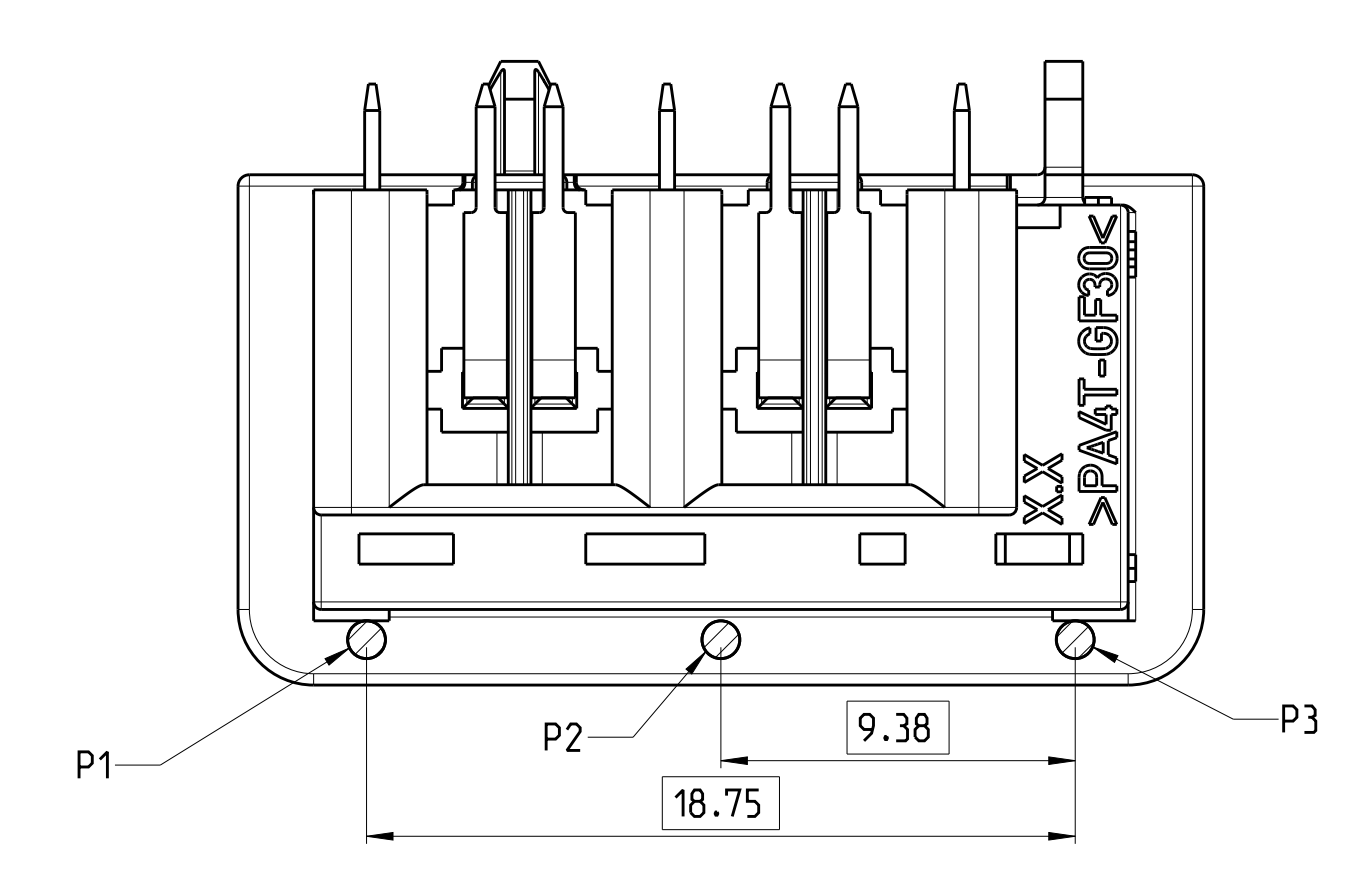
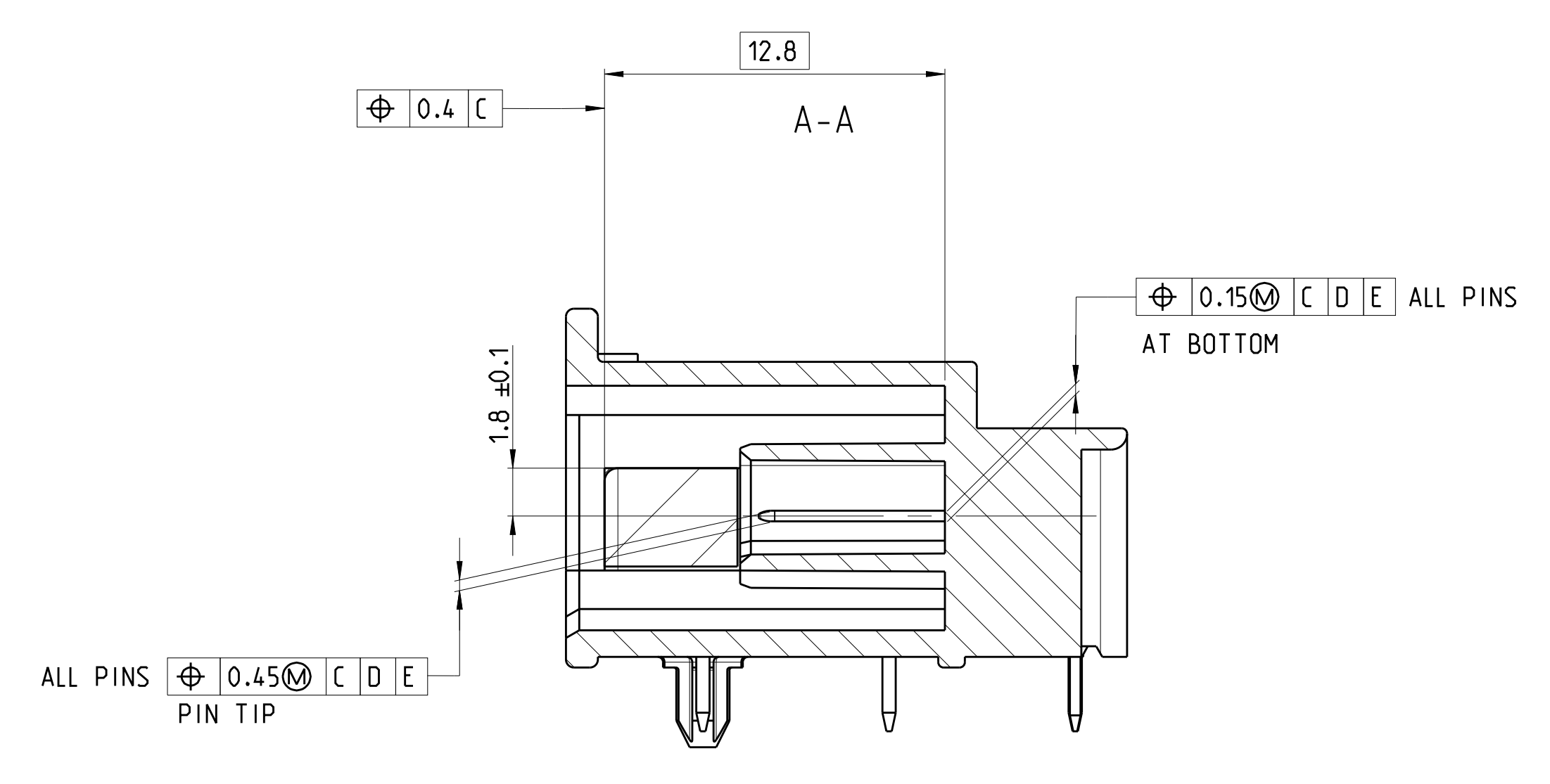
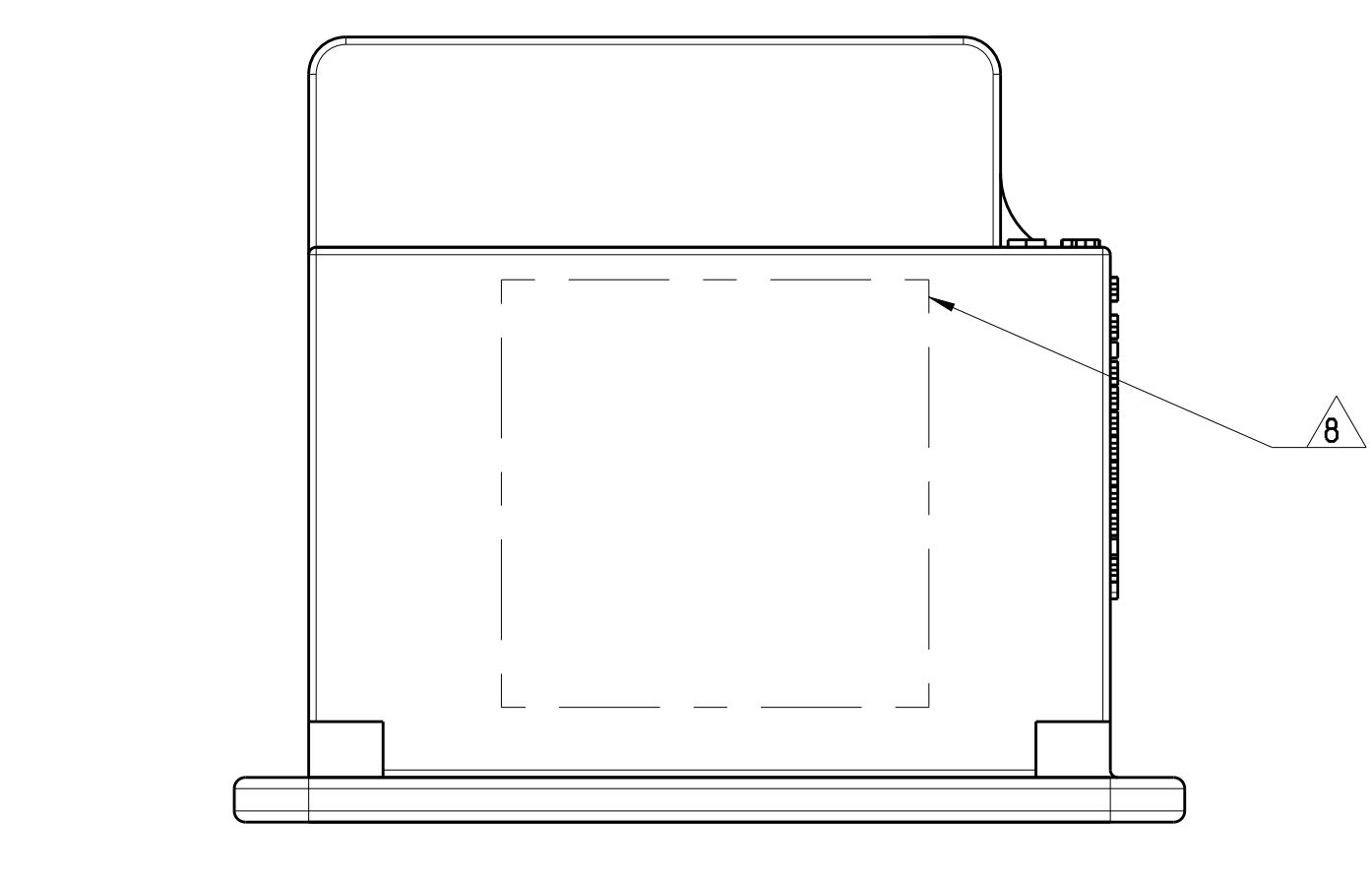
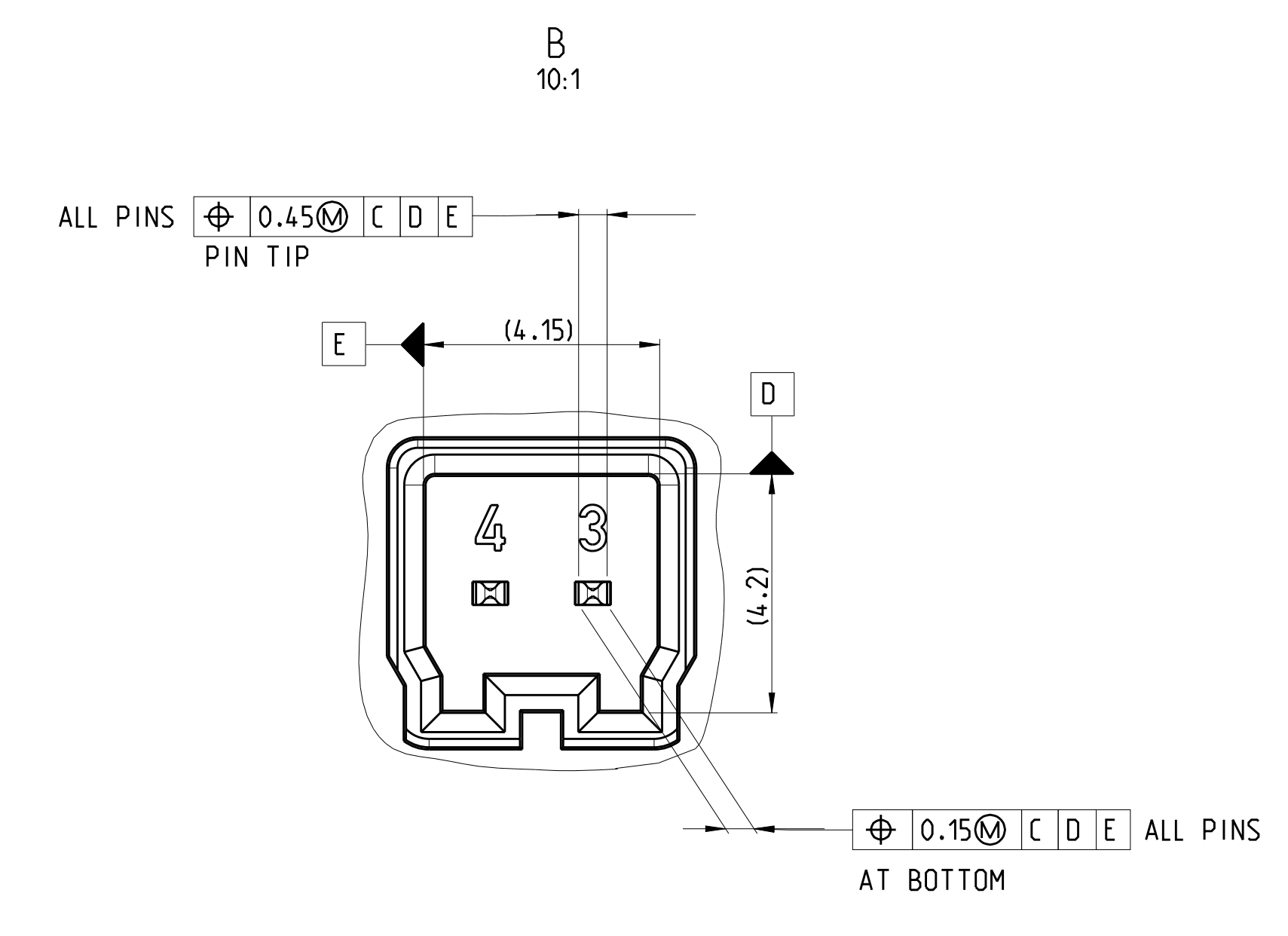
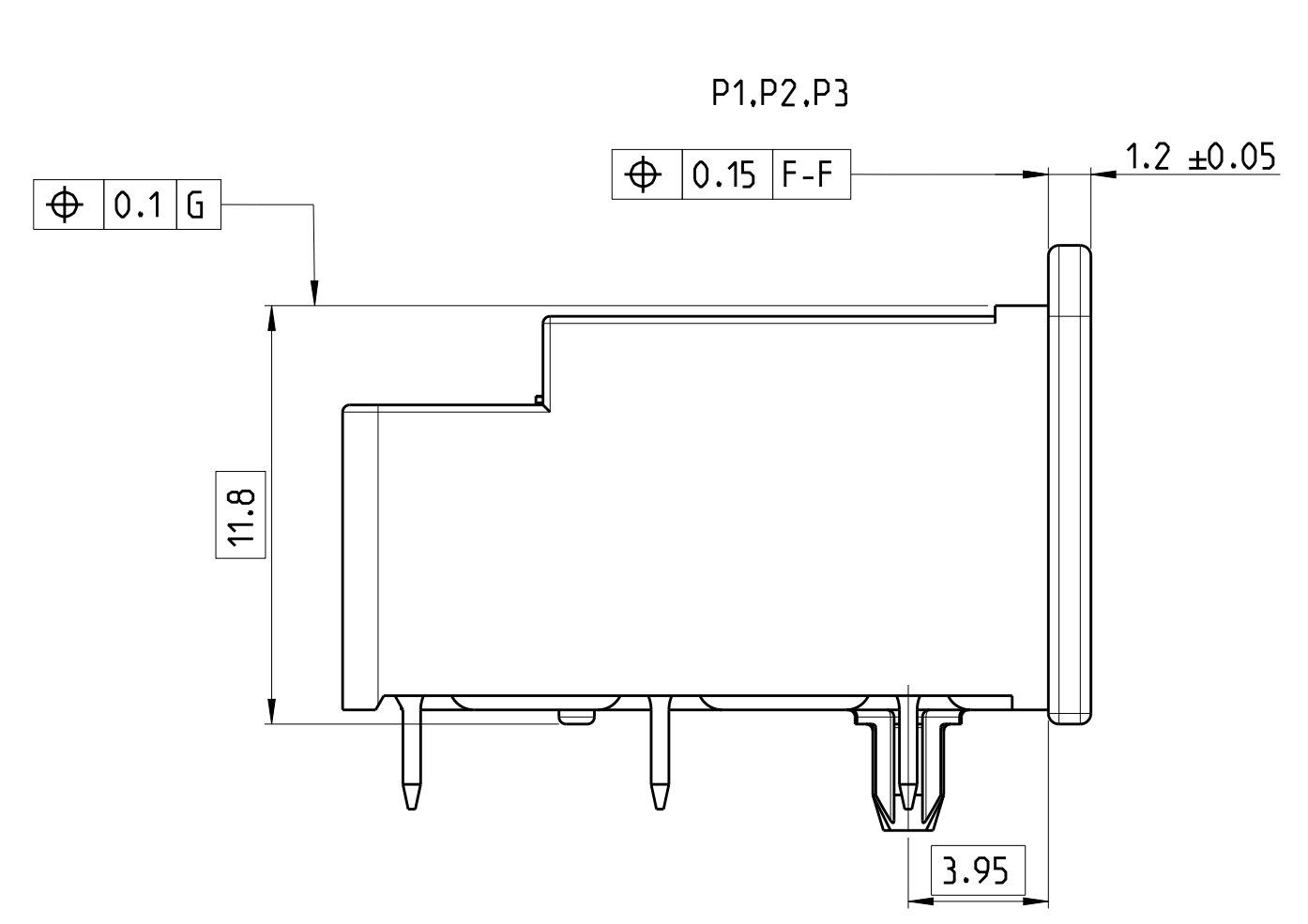
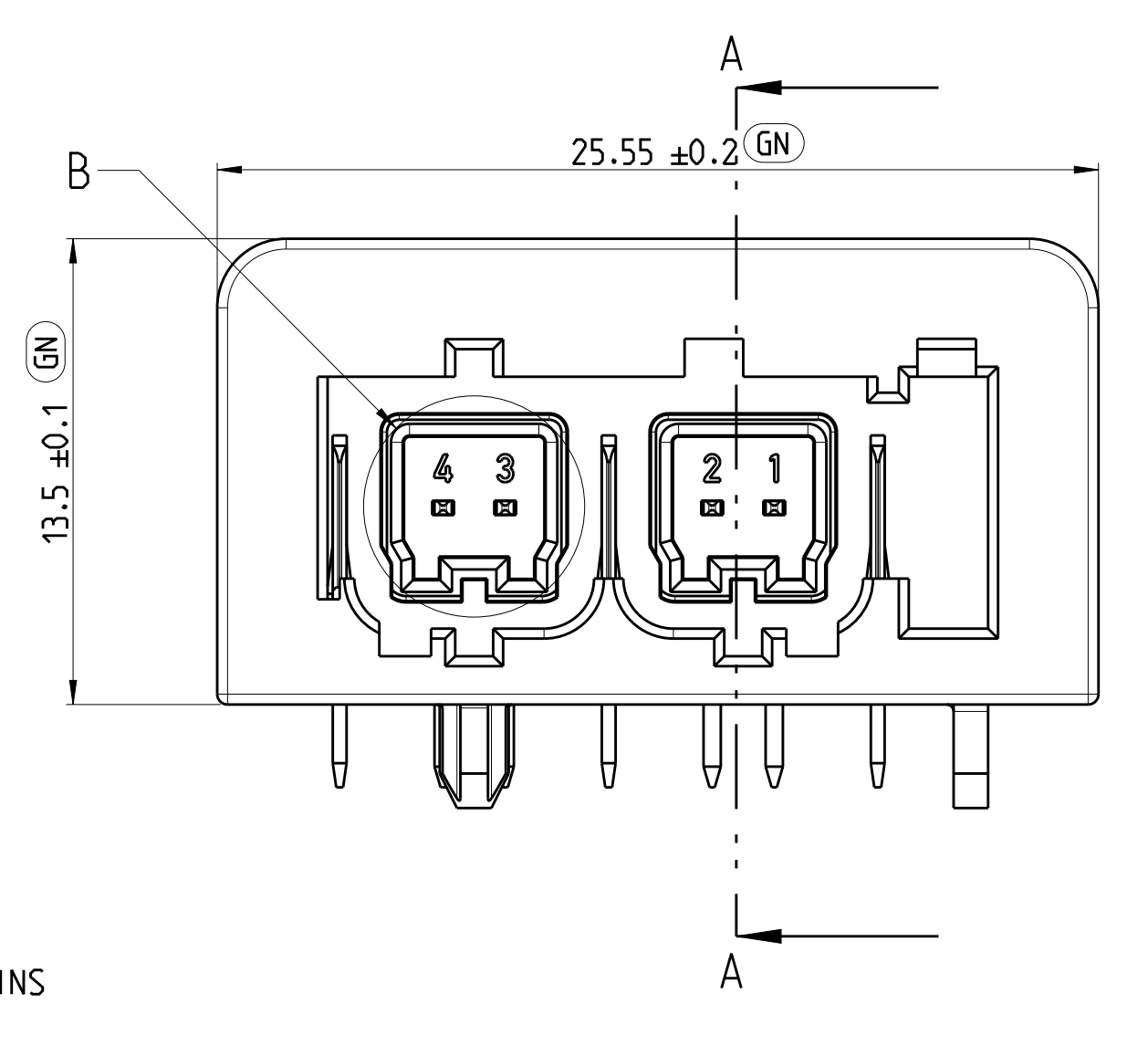
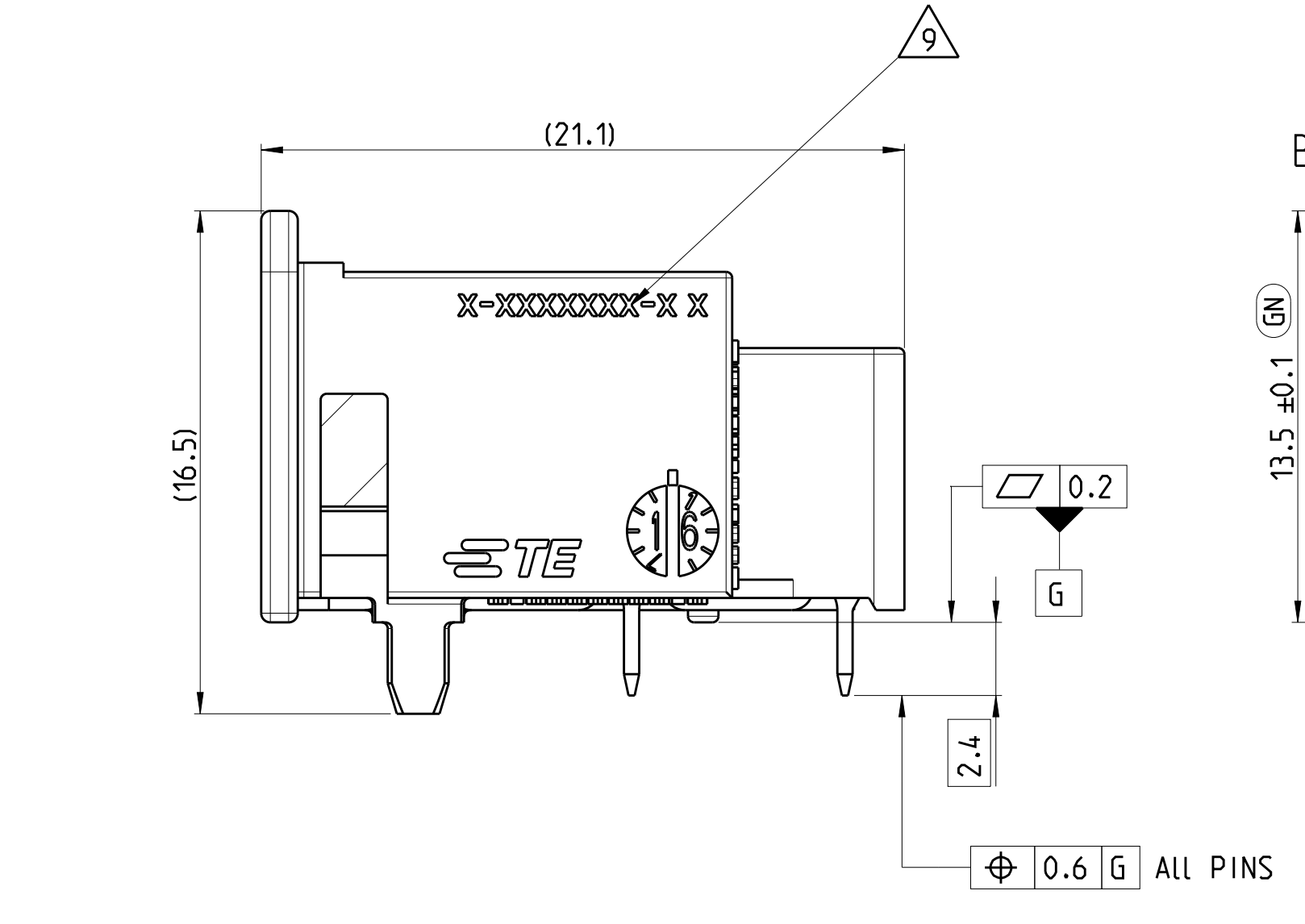
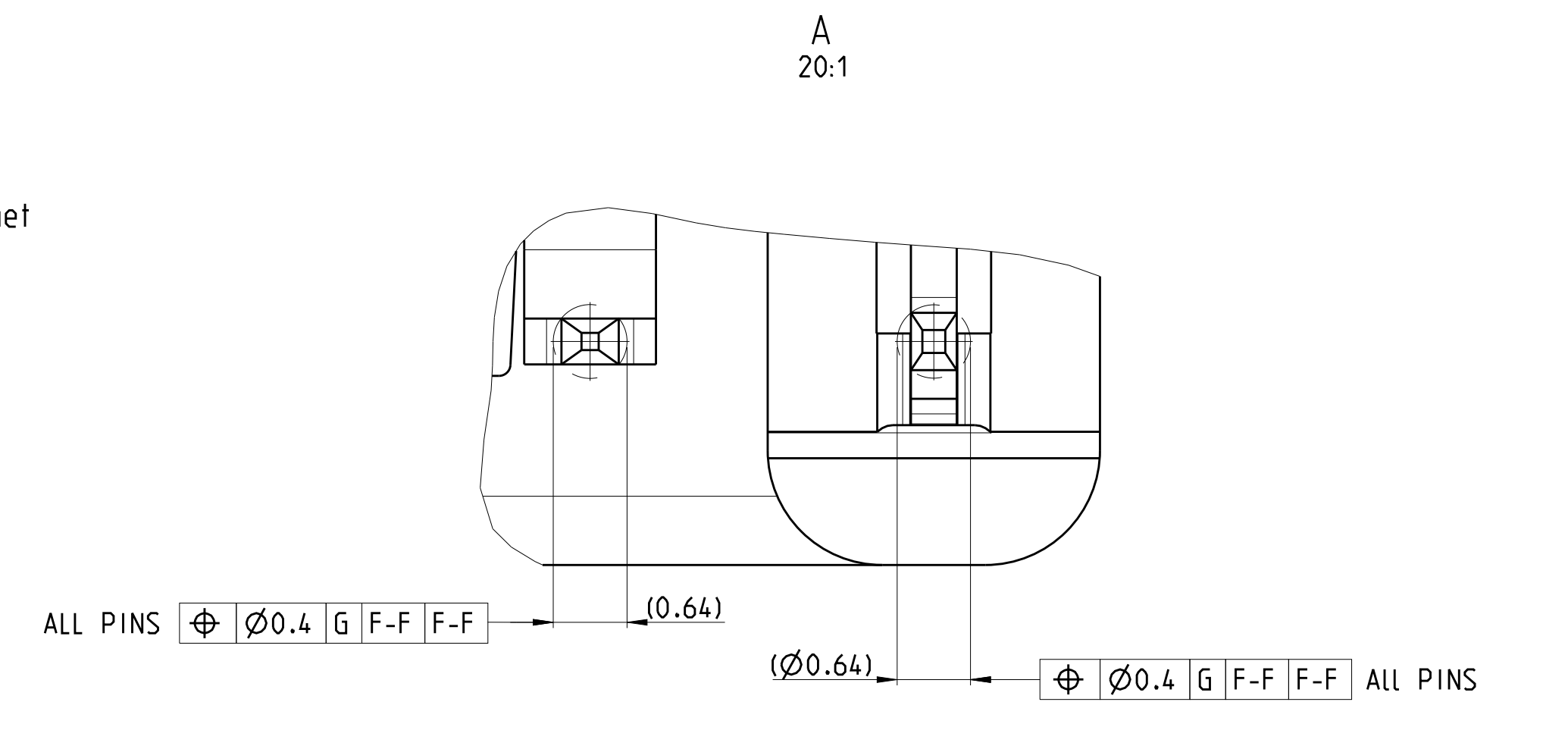


REVISIONS				
P	LTN	DESCRIPTION	DATE	APPV
A		NEW DRAWING	09AUG2016	AB AB
A1		ADDED SERIES PART	11APR2017	MSA AB

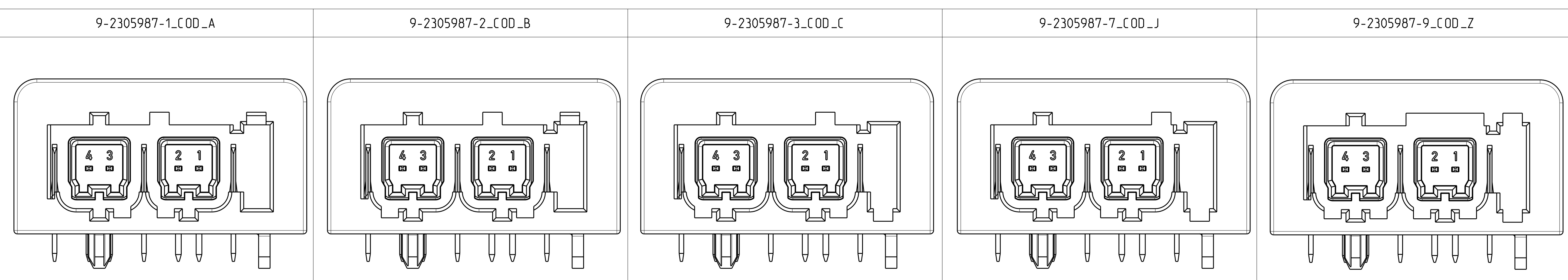
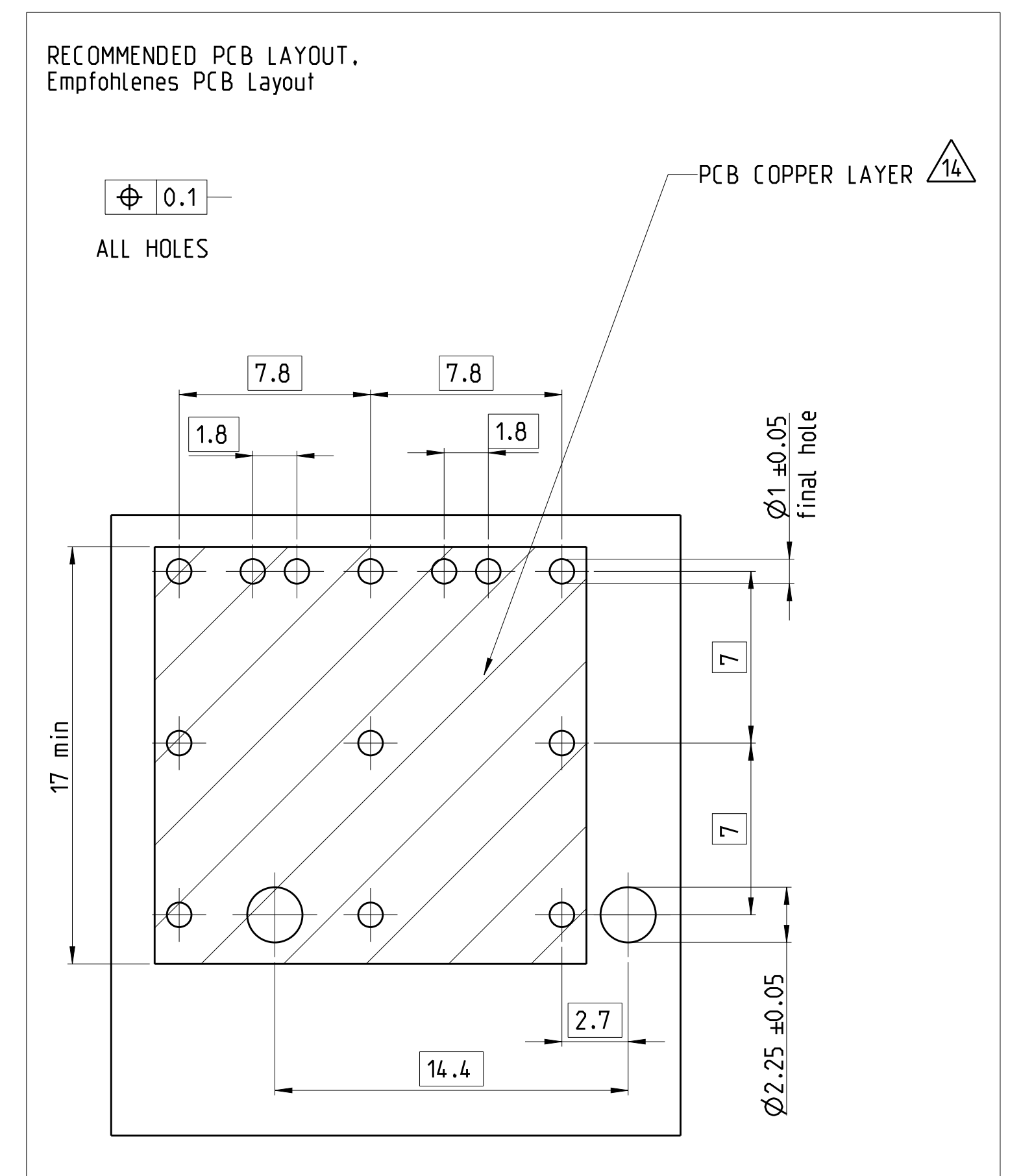
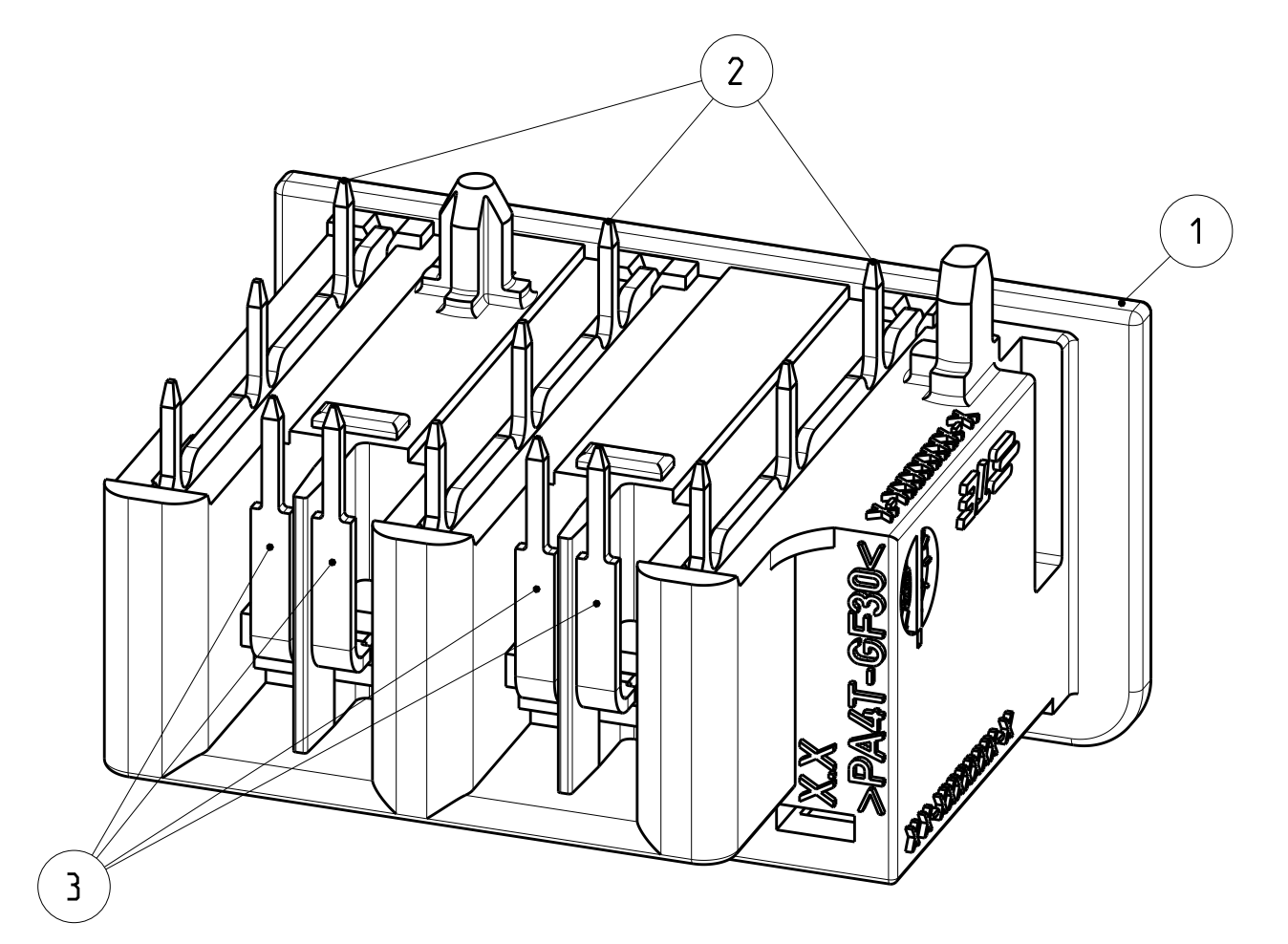


9-2305987-2 COD. B AS SHOWN wie gezeichnet



- GENERAL NOTES
ALLGEMEINE Bemerkungen
- PRESS OUT FORCE FOR NANO MQS >15N WITH FEED RATE 25mm/min
Kontaktausdruckkraft der Nano MQS Kontakte >15N mit Vorschubgeschwindigkeit 25mm/min.
 - DIMENSIONS FROM INTERFACE SEE DRAWING C-208-18012 REV A1
Masse vom Interface siehe Zeichnung C-208-18012 Rev A1
 -
 - TOLERANCE ACC. TO DIN EN ISO 8015, DIN EN ISO 14405-1
GENERAL TOL. ACC. TO DIN 16742 TGS, EXCEPT ANGLE DIM. (SEE TITLE BLOCK)
Tolerierung nach DIN EN ISO 8015, DIN EN ISO 14405-1
Allgemeintoleranzen nach DIN 16742 TGS, ausser Winkelmasse (siehe Schriftkopf)
 - PACKAGING ACC. TO V2305987 TAPE & REEL
Verpackung nach V2305987 Tape & Reel
 -
 - CONTACT SURFACE
MATING SIDE 1-3 µm OVER 1.0-2.2 µm Ni, SOLDER SIDE 3-8 µm Sn OVER 1.0-2.2 µm Ni
Kontaktfläche
Steckseitig 1-3 µm ueber 1.0-2.2 µm Ni, Lotseitig 3-8 µm Sn ueber 1.0-2.2 µm Ni
 - VACUUM GRIP AREA
Ansaugfläche
 - PART NO EXCHANGEABLE ACC. TABLE
Teile Nr. auswechselbar nach Tabelle
 - SOLDERING PROCESS: LEAD-FREE REFLOW SOLDERING IN REFERENCE TO JEDEC J-STD-020D
Lotprozess: Bleifreies Reflowlotten in Anlehnung an die JEDEC J-STD-020D
 - HEADER FULFIL RF-REQUIREMENTS UP TO 1GHz ACC. TE SPEC. 108-94509, ALSO MANDATORY IS A PCB COPPER LAYER ACC. TO TE SPEC. 114-94448
Der Header erfuehlt die RF-Anforderungen bis zu 1 GHz nach TE Spez. 108-94509, Ebenfalls notwendig ist eine Leiterplatten Kupferschicht nach TE Spez. 108-94509
 - HEADER FULFIL RF-REQUIREMENTS UP TO 100 Mhz ACC. TE SPEC 108-94414
Der Header erfuehlt die RF-Anforderungen bis zu 100MHz nach TE Spez.108-94414
 - POSSIBLE FIXTURE OF HEADER WITH THE AGGREGAT CASE
Moegliche Fixierung des Header durch das Aggregat Gehaeuse
 - APPLICATION SPECIFICATION ACC. TO 114-94448
Anwendungsspezifikation TE Spez. 114-94448

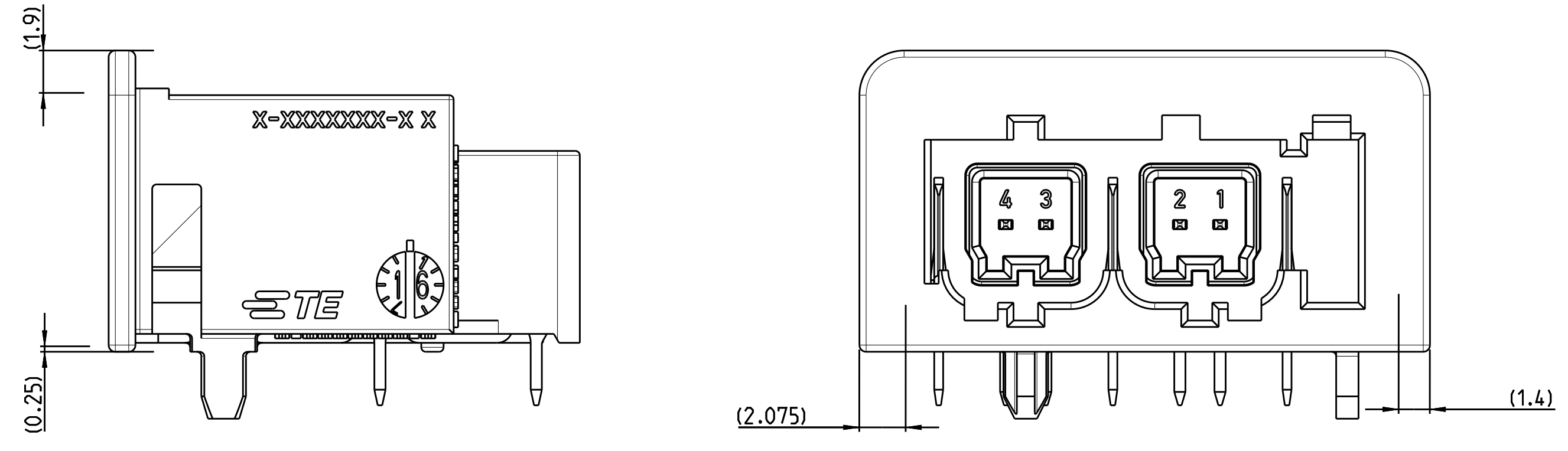
FOR PILOT ONLY
Nur fuer Pilot.



TE ORDER NO.	WEIGHT	CODING	REV	QTY.	DESCRIPTION	MATERIAL	POS.
9-2305987-9	4.02	Z	A	4	Nano MQS TAB 90°	Cu-Alloy	3
				3	Shield	Cu-Alloy	2
				1	2 Port 90° HSG COD.Z	PA4T-GF30	1
9-2305987-7	4.02	J	A	4	Nano MQS TAB 90°	Cu-Alloy	3
				3	Shield	Cu-Alloy	2
				1	2 Port 90° HSG COD.J	PA4T-GF30	1
9-2305987-3	4.02	C	A	4	Nano MQS TAB 90°	Cu-Alloy	3
				3	Shield	Cu-Alloy	2
				1	2 Port 90° HSG COD.C	PA4T-GF30	1
9-2305987-2	4.02	B	A	4	Nano MQS TAB 90°	Cu-Alloy	3
				3	Shield	Cu-Alloy	2
				1	2 Port 90° HSG COD.B	PA4T-GF30	1
9-2305987-1	4.02	A	A	4	Nano MQS TAB 90°	Cu-Alloy	3
				3	Shield	Cu-Alloy	2
				1	2 Port 90° HSG COD.A	PA4T-GF30	1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONS: 0-PLC, 1-PLC, 2-PLC, 3-PLC, 4-PLC, 5-PLC, 6-PLC, 7-PLC, 8-PLC, 9-PLC, 10-PLC, 11-PLC, 12-PLC, 13-PLC, 14-PLC, 15-PLC, 16-PLC, 17-PLC, 18-PLC, 19-PLC, 20-PLC. MATERIAL: FINISH: CUSTOMER DRAWING. SCALE: 5:1 SHEET 2 OF 3 REV A1.

MATED WITH CONNECTOR

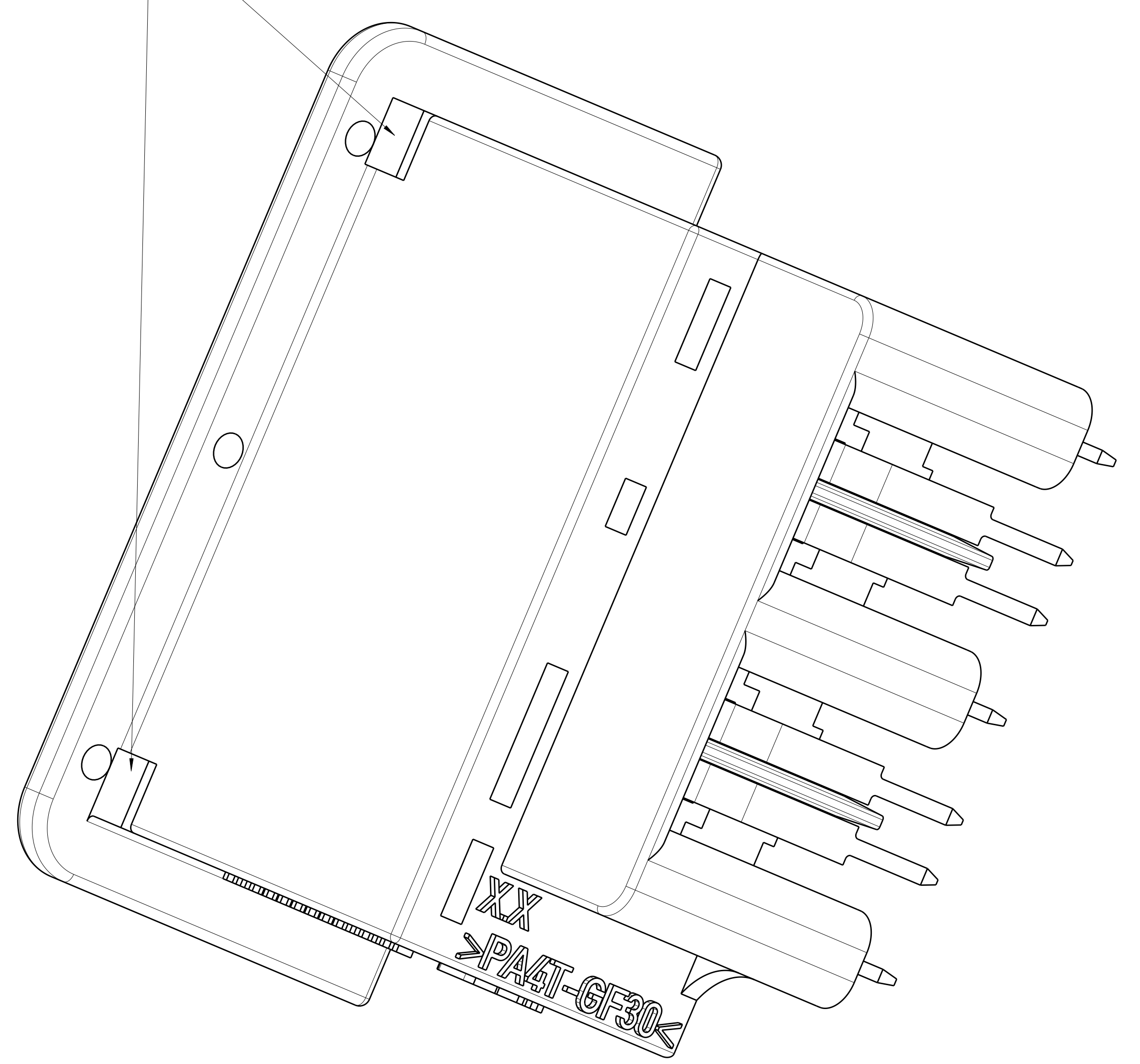


REVISIONS			
P	LN	DESCRIPTION	DATE

POSSIBLE FIXTURE OF HEADER

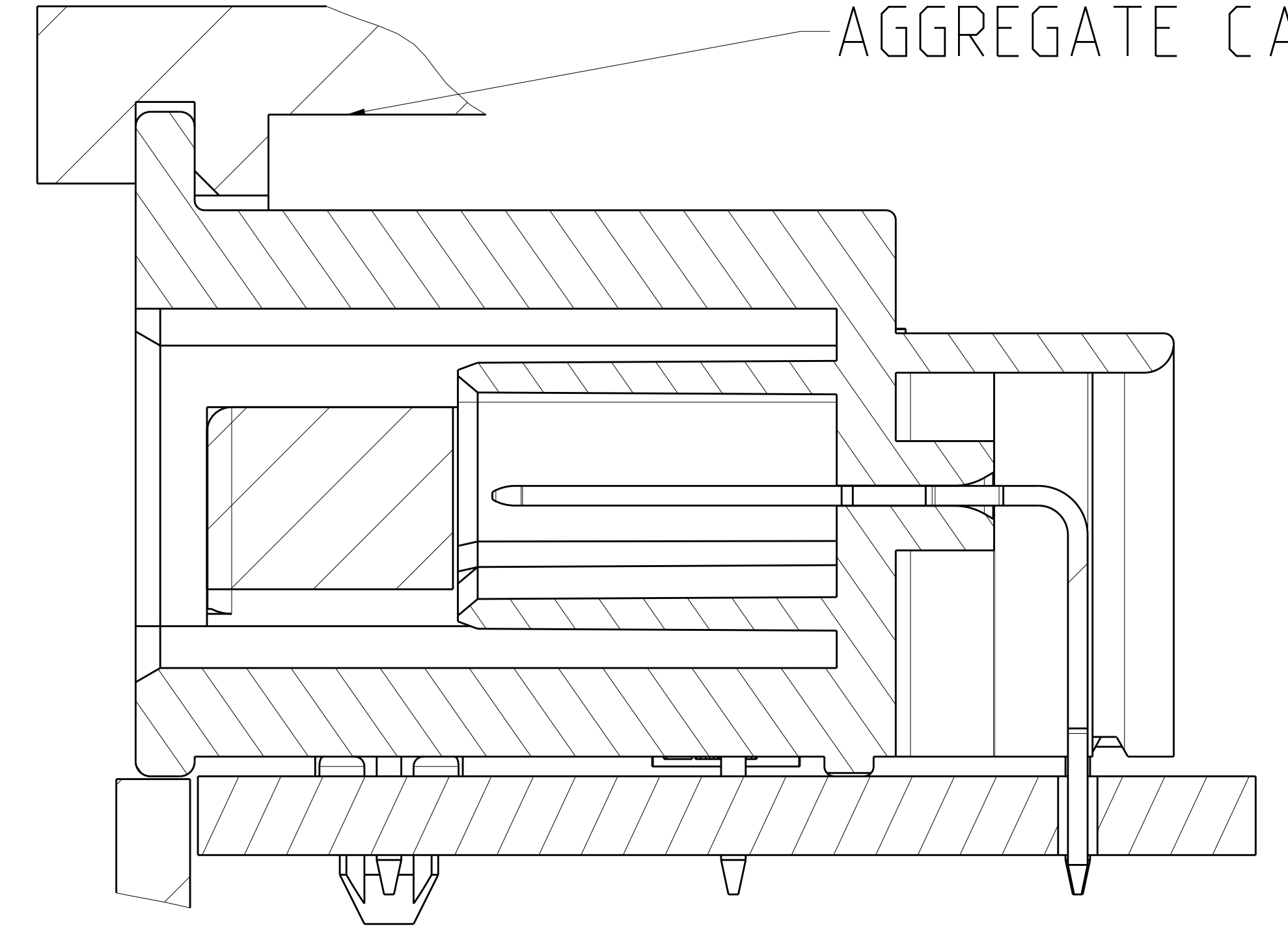
13

CONTACT POINT FOR AGGREGAT CASE



PROPOSAL CASE

AGGREGATE CASE



THIS DRAWING IS A CONTROLLED DOCUMENT. DWN		CHK		NAME	
DIMENSIONS:		APVD		PRODUCT SPEC	
MATERIAL:		APPLIC. SPEC		RESTRICTED TO	
FINISH:		WEIGHT:		SCALE: SHEET OF REV	

